

In the Specification

Amendments to the Specification:

On page 1, please amend the title of the invention as follows:

DIE PILLAR STRUCTURES AND A METHOD OF THEIR FORMATION

On page 9, please amend the third and fourth paragraphs as follows:

Fig. 8 illustrates an example die design 100 employing a design of the pillar structures 34 of the present invention surrounded by the die perimeter ~~102~~. As shown in Fig. 8, the die 100 may include pillar structures/bumps 34 of varying shapes.

The die perimeter ~~102~~ may be used, and provides RF shielding, in Surface Acoustic Wave (SAW) devices, noise reduction, power current capacity, hermetic shield and may be used in RF devices, power devices and MEMs for noise isolation and current capacity.